



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com					Package Code: TSG100		Assembly: ASEK Size (mm): 14x14x1.4 Lead pitch (mm): 0.5mm MSL: 3 Reflow max (°C): 260	
May, 2026	Package: Total Device Weight		LQFP 669.540 Milligrams		Products: XO4			
	% of Material to Pkg. Wt.	Material Weight (mg)	% of Substance Wt./Pkg Wt.	Material Substance Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
IC Chip (Die)	1.228%	8.221	1.228%	8.221	Silicon chip	7440-21-3	100.000%	Die size: 3.150 x 3.050mm
Mold Compound	68.435%	458.200	1.88%	12.611	4-methyl-(1,1'-biphenyl)-4,4'-diyl-bis(oxyethylene)	85954-11-6	2.752%	EME-G631SH Type B_ATV
			1.88%	12.611	Epoxy Resin	Trade Secret	2.752%	
			4.71%	31.528	Phenol Resin	Trade Secret	6.881%	
			47.09%	315.275	Silica(Amorphous) A	60676-86-0	68.807%	
			9.42%	63.055	Silica(Amorphous) B	7631-86-9	13.761%	
			3.45%	23.120	Carbon Black	1333-86-4	5.046%	
Die Attach	0.264%	1.769	0.019%	0.129	2-Phenoxyethyl Acrylate	48145-04-6	7.317%	EN-4900F-ATV
			0.004%	0.026	Substitutedalkoxyalkyltrimethoxysilane	2530-83-8	1.463%	
			0.193%	1.294	Silver	7440-22-4	73.171%	
			0.026%	0.173	Polybutadieneepoxidized derivative	Trade secret	9.756%	
			0.001%	0.009	Butadiene copolymer	Trade secret	0.488%	
			0.019%	0.129	Bisphenol F diacrylate	Trade secret	7.317%	
			0.001%	0.009	Peroxy Ketals	Trade secret	0.488%	
Wire	0.067%	0.450	0.066%	0.442	Copper	7440-50-8	98.275%	Cu wire_AuPCC+
			0.001%	0.007	Palladium	7440-05-3	1.555%	
			0.0001%	0.001	Gold	7440-57-5	0.170%	
External Plating	3.122%	20.900	3.122%	20.900	Tin(Sn)	7440-31-5	100.000%	
Leadframe	26.89%	180.000	25.45%	170.370	Copper (Cu)	7440-50-8	0.95	C7025+AG
			0.86%	5.760	Nickel (Ni)	7440-02-0	3.20%	
			0.19%	1.305	Silicon (Si)	7440-21-3	0.73%	
			0.05%	0.315	Magnesium (Mg)	7439-95-4	0.18%	
			0.34%	2.250	Plating Silver(Ag)	7440-22-4	1.25%	
	100.00%	669.54	100.00%	669.540			600.00%	

Notes:

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